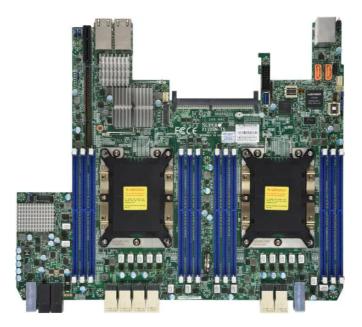
X11DSN-TSQ (For SuperServer Only)



Intel® Quick Assist Technology SIOM LAN Support NVMe

Key Features

1. 2nd Gen Intel® Xeon® Scalable Processors and Intel® Xeon® Scalable Processors, Dual Socket LGA-3647 (Socket P) supported, CPU TDP support Up to 205W TDP, 3 UPI up to 10.4 GT/s

2. Intel® C627

- 3. Up to 3TB 3DS ECC RDIMM, DDR4-2933MHz; Up to 3TB 3DS ECC LRDIMM, DDR4-2933MHz, in 12 DIMM slots; Up to 2TB Intel® Optane[™] DC Persistent Memory in memory mode (Cascade Lake only)
- 4. 2 PCI-E 3.0 x16 Left Riser Slot M.2 Interface: 1 PCI-E 3.0 x4 M.2 Form Factor: 2242/2260/2280 M.2 Key: M-Key
- 5. Dual LAN with 10GBase-T with Intel® X557

6. 1 VGA D-Sub Connector port

7. Intel® PCH SATA controller for

Specifications

Expansion Slots

PCI-E	2 PCI-E 3.0 x16 Left Riser Slot	
M.2	 M.2 Interface: 1 PCI-E 3.0 x4 Form Factor: 2242/2260/2280 Key: M-Key 	
System BIOS		
BIOS Type	AMI UEFI	
Management		
Software	 SuperDoctor® 5, NMI, <u>SUM</u>, KVM with dedicated LAN, <u>SPM</u>, Intel® Node Manager, <u>SSM</u>, <u>IPMI2.0</u>, Watchdog, IPMI (Intelligent Platform Management Interface) v2.0 with KVM support, SuperDoctor® III 	
System Management Software	 IPMI (Intelligent Platform Management Interface) v1.5 / 2.0 with KVM support 	
Power Configurations	 M.2 NGFF connector, Node Manager Support, SDDC, System level control, UID, WOL 	
PC Health Monitor	ring	
Voltage	 VBAT, Monitors CPU voltages, 1.2V (VDIMM), 1.05 (PCH), +5V standby, +5V, +3.3V, +12V, +1.35V, Memory Voltages 	
LED	CPU / System Overheat LED	
Temperature	 Monitoring for CPU and chassis environment 	

Operating Environment

FAN

Other Features

Operating Temperature Range	∎ 10°C - 35°C (50°F - 95°F)
Non-Operating Temperature Range	∎ -20°C - 60°C (-4°F - 140°F)
Operating Relative Humidity Range	∎ 8% - 90% (non-condensing)

4x 4-pin fan headers (up to 4 fans)

 WOL, UID, RoHS, Node Manager Support, M.2 NGFF connector, Control of power-on for recovery from AC power loss, Chassis intrusion detection, RoHS, Halogen

PWM fan speed controlOverheat LED indication

Free, Intel® QuickAssist Technology, Innovation Engine

. Relative Humidity Range

10% - 95% (non-condensing)

Product SKUs

MBD-X11DSN-	X11DSN-TSQ
TSQ	

Physical Stats

Form Factor	Proprietary	
Dimension	∎ 11.5" x 13.9" (29.21cm x 35.31cm)	

Processor

CPU	 2nd Gen Intel® Xeon® Scalable Processors and Intel® Xeon® Scalable Processors Dual Socket LGA-3647 (Socket P) supported, CPU TDP supports Up to 205W TDP, 3 UPI up to 10.4 GT/s
Note	 BIOS version 3.2 or above is required to support 2nd Gen Intel® Xeon® Scalable processors (codenamed Cascade Lake-R)

System Memory

Memory Capacity	 12 DIMM slots Up to 3TB 3DS ECC LRDIMM, DDR4-2933MHz; Up to 3TB 3DS ECC RDIMM, DDR4-2933MHz Up to 2TB Intel® Optane[™] DC Persistent Memory in memory mode (Cascade Lake only) 	
Memory Type	 ECC DDR4 LRDIMM (3DS), RDIMM (3DS) 	
DIMM Sizes	∎ LRDIMM: 64GB, 128GB ■ RDIMM: 64GB, 128GB	
Memory Voltage	∎ 1.2V	
Error Detection	 Corrects single-bit errors Detects double-bit errors (using ECC memory) 	

On-Board Devices

Chipset	∎ Intel® C627	
SATA	 Intel® PCH SATA controller for ports 	
IPMI	ASPEED AST2500	
Graphics	ASPEED AST2500 BMC	
Network Controllers	 Dual LAN with 10GBase-T with Intel® X557 	

Input / Output

USB	 1 USB 3.2 Gen1 port(s) (1 type A) 2 USB 3.0 port(s) (2 rear) 		
Video Output	1 VGA D-Sub Connector port(s)		
Serial Port	2 COM Port(s) (1 header; 1 rear)		
ТРМ	1 TPM Header		

https://www.supermicro.com/en/products/motherboard/x11dsn-tsq

Parts List

Parts List (Bulk Package)			
Name	Part Number	Qty	Description
Motherboard	MBD-X11DSN-TSQ	1	X11DSN-TSQ Motherboard

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